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First Call For Papers
2023 IEEE 15th International Conference on ASIC
Oct. 24-27, 2023，Platinum Hanjue Hotel
Nanjing , China

Sponsored by	*IEEE Beijing Section*
Co-Sponsored by	*Fudan University*
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2023 IEEE 15th International Conference on ASIC (**ASICON 2023**) will be held in Nanjing, China, during Oct.24-27, 2023. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper Award & Outstanding Young Scholar Paper Award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

The Scope of the Conference

Papers are solicited in, but not limited to, the following:
I.   Integrated Circuits and Design Techniques
[1]   Analog IC
[2]   Digital IC
[3]   Wireless, Wireline telecommunication and Optic Communication IC
[4]   Memory
[5]   Sensor, Image Processing and Bio-medical IC
II.   FPGA
[6]   FPGA and DSP
[7]   Special application IC
[8]   Design for Testing
III.   CAD Techniques
[9]   Circuits Simulation, Synthesis, Verification and Physical Design
[10]   CAD for System, Design for Manufacturing and Testing
IV.   New Techniques, New Processing, New Devices and Their Applications
[11]   MEMS Techniques
[12]   Nano-electronics and Giga-scale Systems
[13]   New Devices
[14]   New Processing
[15]   Processing Modeling & Simulation
V.   Other VLSI Design and Device Related Topics
[16]   Other Devices Related Topics
[17]   Other VLSI Design Related Topics

Keynote Speeches

Session K1-1: Technology Innovations at the heart of Engineering Humanitarian Solutions
Time: 9:00-9:45，Oct.25, 2023，Wednesday
Speaker：Dr. Rakesh Kumar
          IEEE Life Fellow, IEEE TA Hall of Honor Chair, IEEE Roadmaps Chair
          President, Technology Connexions, Inc，USA

Session K1-2: Let the Plants Do the Talking: Smart Agriculture by the Messages Received from Plants and Soil
Time: 9:45-10:30，Oct.25, 2023，Wednesday
Speaker：Prof. Danilo Demarchi
　　　　　Politecnico di Torino，Italy

Session K2-1 Oxide Thin-Film Transistors and Integrations
Time: 10:45-11:30，Oct.25, 2023，Wednesday
Speaker：Prof. Aimin Song
　　　　　University of Manchester，UK

Session K2-2 Efficiency, Resilience, and Versatility in Memristive Neuromorphic Systems for AI on the Edge
Time: 11:30-12:15，Oct.25, 2023，Wednesday
Speaker：Prof. Gert Cauwenberg
　　　　　University of California, San Diego, USA

Session K3-1 RF Acoustic Wave Devices in Mobile Communications --- Aliens from Jupiter
Time: 8:30-9:15，Oct.26, 2023，Thursday
Speaker：Prof. Ken-ya Hashimoto (Fellow of IEEE)
　　　　　University of Electronic Science and Technology of China

Session K3-2 The back-gate of UTBB FDSOI transistor : a magic knob for analog and mixed cells
Time: 9:15-10:00，Oct.26, 2023，Thursday
Speaker：Prof.Gilles Jacquemod
　　　　　Université Côte d'Azur, France

Session K4-1 Sub-Terahertz Communication and Its Future Towards 6G
Time: 8:30-9:15，Oct.27, 2023，Friday
Speaker：Prof. Minoru Fujishima
　　　　　Hiroshima University，Japan

Session K4-2 Terahertz-chip-scale systems for Intelligent Sensing and 6G Communication
Time: 9:15-10:00，Oct.27, 2023，Friday
Speaker：Prof. Kaushik Sengupta
　　　　　Princeton University, USA

Papers Submission

Prospective authors are requested to submit full-length papers in English of no more than four pages using the proceedings format, double columned, 10pt fonts including figures, tables and references. For further information on the paper format, please refer to "template". The papers are submitted in their final form, if accepted, will be published as submitted. All submissions must be made at the conference website. Authors who want to compete for the Excellent Student or Outstanding Young Scholar Paper Award should apply at the conference website. Detailed instructions for paper preparation and submission can be found at conference website. **Tutorial proposals are also invited.**

Contact persons:　　　　Prof. Huihua Yu　　　　　　　　　Prof. FanYe
　　　　　　　　　　　　(Conference Issue)　　　　　　　　(Paper Submission)
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For further information please visit conference web site:

http://www.asicon.org

Deadline of papers submittal is June 30, 2023
Paper acceptance/rejection will be informed by Aug. 15, 2023